

Title (en)

SUPPORT AND/OR CLIP FOR SEMICONDUCTOR ELEMENTS, SEMICONDUCTOR COMPONENT, AND PRODUCTION METHOD

Title (de)

TRÄGER UND/ODER CLIP FÜR HALBLEITERELEMENTE, HALBLEITERBAUELEMENT UND VERFAHREN ZUR HERSTELLUNG

Title (fr)

SUPPORT ET/OU ÉTRIER POUR ÉLÉMENTS SEMI-CONDUCTEURS, ÉLÉMENT SEMI-CONDUCTEUR ET PROCÉDÉ DE FABRICATION

Publication

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Application

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Abstract (en)

[origin: WO2015144835A1] The invention relates to a support and/or clip for at least one semiconductor element with at least one functional surface (10) for connecting to the semiconductor element. The invention is further characterized by at least one solder resist cavity (12) with at least one flank wall (13), in particular a straight flank wall (13), and a delimiting edge (14) which adjoins the flank wall (13) and delimits the functional surface (10) at least on one side. The delimiting edge (14) forms a protrusion (15) which protrudes past the functional surface (10) in order to retain solder, and/or the flank wall (13) forms an undercut (16) for retaining solder at the delimiting edge (14).

IPC 8 full level

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Citation (search report)

See references of WO 2015144835A1

Designated contracting state (EPC)

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